

Nasser H. Paydar

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Indiana University East
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EDUCATION:

Ph.D. Mechanical Engineering, Syracuse University, 1985
M.S. Mechanical Engineering, Syracuse University, 1981
B.S. Mechanical Engineering, Syracuse University, 1979

**RESEARCH
INTERESTS:**

Solid mechanics, computational methods based on the finite element analysis with applications in electronic packaging and biomechanics.

**TEACHING
INTERESTS:**

Classical mechanics.

**PROFESSIONAL
EXPERINCES:**

Interim Chancellor, Indiana University East, 2007 – 2009
Chancellor, Indiana University East, 2009 – present
Vice Chancellor and Dean, Indiana University Purdue University Columbus,
2003-2007.
Executive Associate Dean for Academic Programs, Purdue University School of
Engineering and Technology (SET), Indiana University Purdue University
Indianapolis (IUPUI), 2002-2003.
Associate Dean for Academic Programs, SET, IUPUI, 1996-2002.
Associate Dean for Graduate Programs, SET, IUPUI, 1995-1996.
Chair of the Department of Mechanical Engineering, IUPUI, 1989-1996.
Professor of Mechanical Engineering, IUPUI, 1996-present.
Tenured, Department of Mechanical Engineering, IUPUI, 1990-present.
Associate Professor of Mechanical Engineering, IUPUI, 1990.
Assistant Professor of Mechanical Engineering, IUPUI, 1985-1990.

**AWARDS,
HONORS, AND
OTHER
ACTIVITIES OF
DISTINCTIONS:**

Reviewer, the National Science Foundation
Reviewer, ASME Journals of Engineering Resources Technology and
Engineering Materials & Technology
Reviewer, International Journal of Solids and Structures
Reviewer, International Journal of Sound and Vibrations
Recipient of the Dorris H. Merritt **Outstanding Leadership** Award, Purdue
University School of Engineering and Technology, 2000
Recipient of the Abraham M. Max **Distinguished Professor** Award, Purdue
University School of Engineering and Technology, 1994
Recipient of the **Outstanding Teaching** Award, Department of Mechanical
Engineering, IUPUI, 1990
Recipient of the **Outstanding Teaching** Award, Department of Mechanical
Engineering, IUPUI, 1989
Recipient of the **Outstanding Teaching** Award, Department of Mechanical
Engineering, IUPUI, 1988
Recipient of the Wisner - Stoelk Award **Outstanding Faculty** in the Purdue
University School of Engineering and Technology, 1988

**INTERNATIONAL
COLLABORATIONS:**

China:

Established academic relations, based on a 2+2 program, with Hunan University
in Changshu and Hohai University in Nanjing

France:

Established student exchange program with the Universite de la Mediterranee
Aix-Marseille

Germany:

Established student exchange program with Heilbronn University of Applied
Science and Bremen University

Thailand:

Established a 2+2 academic program with Mahasarakham University

Tunisia:

Established an academic agreement with the government of Tunisia for hosting
graduate students from Tunisia

**COMMITTEES
AND BOARDS:**

National

- Member – Policies and Purposes Committee of American Association of State Colleges and Universities
- Member – International Committee of American Association of State Colleges and Universities
- Member – New University President’s Academy Advisory Committee of American Association of State Colleges and Universities

State

- Member – Council on Economic Vitality in East Central Indiana
- Member – Indiana Commission for Higher Education, State-wide Transfer and Articulation Committee
- Member – Indiana Chancellors/Presidents Campus Compact
- Member – Board of Directors of Wayne County Chamber of Commerce, IN
- Member – East Central Indiana Life Sciences Task Force, IN
- Member – Educational Leadership Committee, Richmond, IN
- Member – Board of Directors of Visitors Center, Columbus, IN
- Member – Board of Directors of Chamber of Commerce, Columbus, IN
- Member – Board of Directors of Economic Development, Columbus, IN
- Chair – Government Subcommittee of Chamber of Commerce Columbus, IN,

University

- Chair – S & S Committee for IU Kokomo Chancellor
- Chair – S & S Committee for IU Associate Executive Vice President
- Chair – S & S Committee for IU Assistant Executive Vice President
- Chair – Executive Committee for Biomedical Engineering Ph.D. Program
- Chair - Committee for Development of Engineering Ph.D. Programs
- Chair - Committee for Development of Master’s of Technology Program
- Chair – IUPUI Registrar Administrative Review Committee
- Chair – IUPUI Marketing and Recruitment Committee
- Chair - International Program Advisory Recruitment Subcommittee
- Chair – IUPUI Subcommittee on Ethics in Research
- Chair – IUPUI Brain Gain Task Force
- Chair – Accreditation (ABET) Preparation Committee
- Chair - Mechanical Engineering Graduate Committee
- Chair – Three Mechanical Engineering Search and Screen Committees
- Chair - Engineering and Technology Computer Network Adv. Board
- Chair - Freshman Engineering Program Committee
- Chair - School Scholarship Committee

Chair - Women in Engineering and Technology Committee
Chair - Graduate Non-Degree Student Services Task Force
Chair - Purdue University Intercampus Faculty Council
Member – Blue Ribbon Committee on Healthcare Cost Containment
Member – S & S Committee for IU Foundation Vice President
Member – Board of Directors of IU Foundation with over \$1.5 b assets
Member - Purdue University Graduate Council
Member - IUPUI Committee on Ethics in Research
Member - IUPUI Standing Committee on Conflicts of Interest
Member - IU President's Council on International Programs
Member - IUPUI Steering Committee for Clinical Core Research Center
Member - SET II and III Dedication Ceremonies Committee
Member - School Network Software Recourses Committee
Member - School Recruiting and Open House Committee
Member - Faculty Performance Committee
Member - SET II Open House Committee
Member - Orthopaedic Surgery Dept. Search and Screen Committee
Member - Orthodontics Dept. Search and Screen Committee
Member - Engineering Management Program Development
Member - Curricular Review Board
Member - Mechanical Engineering Search and Screen Comte.
Member - Committee for Revising Instructor Evaluation Form
Member - Engineering and Technology School Agenda Committee
Member - Engineering and Technology School Assessment Committee
Member - Dean’s Industrial Advisory Council (DIAC)
Member - Technical Communication Advisory Committee
Member - Academic Policies and Procedures Committee (APPC)
Member - Biomechanics and Biomaterial Research Center
Member - German Exchange Student Committee
Member - Graduate Affairs Committee
Member - Graduate Non-Degree Admissions Subcommittee
Member - International Affairs Program Committee (IAPC)
Member - Interdisciplinary Faculty Collaboration Committee
Member - International Affairs Recruitment Committee
Member - IUPUI Fellowship Subcommittee
Member - IUPUI Scholarship Committee
Member - Program Review and Assessment Committee (PRAC)
Member – S & S Committee for Biomedical Engineering Program Director
Member - IUPUI Biomechanics Research Center Steering Committee
Member - IUPUI Steering Committee for Clinical Core Research Center
Member – S & S Committee for Associate Dean of IU Graduate School
Member - IUPUI Capstone Experience Committee
Member - Search and Screen Committee for Indiana University Associate Vice
President for Information Technologies and Dean of Academic Computing
Member - Committee on Continuing Engineering Education

**PROFESSIONAL
MEMBERSHIP:**

Member – American Association of State Colleges and Universities (AASCU)
Member – American Council on Education (ACE)
Member – American Association for Higher Education
Member - American Society of Mechanical Engineers, ASME
Member - American Society of Engineering Education, ASEE

**GRADUATE
STUDENT
SUPERVISION:**

Cem Poyraz, thesis title: *Three-Dimensional Finite Element Investigation of the Human Mandible and Temporomandibular Joint.*

Jeffrey A. Haskett, thesis title: *Stress Fracture Investigation of a Rabbit Tibia Using Finite Element Analysis.*

Alexander Tsang, thesis title: *Strain Variation in the Cement Mantle Around Femoral Hip Stems due to Increased Cement Thickness - An Experimental Investigation Using Fiberglass Analog Femora.*

Xu Song, thesis title: *Numerical Modeling of Creep Phenomena in Adhesive Epoxy and Solder Joint Assemblies of Electronic Packages.*

David Dankert, thesis title: *Experimental and Finite Element Study of Stress Fracture in Rabbit Tibia Under Repetitive Loads.*

Geoffrey Glogas, thesis title: *Experimental Determination of Viscoelastic Properties of Conductive Adhesive Used in Electronic Packages.*

Altug Bilgic, thesis title: *Experimental Evaluation of Finite Element and Fatigue Life Prediction Methods for Thermally Loaded Solder Joints.*

William Boehmer, thesis title: *Automated Generation of Three Dimensional Finite Element Meshes from Solder Inspection Systems.*

Batu Balkanli, thesis title: *Numerical Simulation of Refining Bubble Behavior in Glass Melting.*

Ali Beskok, thesis title: *A Parallel Finite Element Algorithm for the Time-Averaged Solution of Rotor-Stator Interaction Problem.*

Ali Can, thesis title: *An Investigation of a Block-Structured Solution of Three Dimensional Transonic Flow Equations Using Finite Element Method.*

Anand Chandran, thesis title: *Study of Osteonal Bone Anisotropy Using Experimental and Composite Models.*

RESEARCH GRANTS:

Research (external) Grants:

Carrier Electronics, "Prediction of Fatigue Life of Solder Joints Under Thermal Loads," \$24,111, Co-Principal Investigator, January 11, 1996 - July 10, 1996.

Rockwell International, "Industry/University Cooperative Research Center for Advanced Electronics Interconnects," \$20,000, Principal Investigator, November 1, 1994 - October 31, 1996.

U.S. Naval Air Warfare Center, "Conductive Epoxy Materials Research," \$55,076, Principal Investigator, September 14, 1993 - September 13, 1996.

The National Institutes of Health, "Class VI Composite Placement Methods and Cavity Design" \$69,798, Co-Principal Investigator, October 1, 1994 - September 30, 1996.

The National Institutes of Health, "Prevention of Stress Fracture in Bone," \$382,948, Co-Principal Investigator, April 1, 1993 - March 31, 1996.

Microelectronics and Computer Technology Corporation, "Industry/University Cooperative Research Center for Advanced Electronics Interconnects," \$30,000, Principal Investigator, November 1, 1994 - October 31, 1996.

U.S. Naval Air Warfare Center, "Lead Solder Alternatives" \$8,000, Principal Investigator, January 15, 1994 - January 14, 1995.

Cummins Electronics Corporation, "Industry/University Cooperative Research Center for Advanced Electronics Interconnects," \$10,000, Principal Investigator, August 1, 1994 - July 31, 1996.

DePuy Inc., "Protocol for Determination of Optimum Cement Mantle Thickness by Evaluation of Strain Distribution Induced by Static Loads," \$66,418, Co-Principal Investigator, May 1, 1993 - December 31, 1995.

Delco Electronics Corporation, "Industry/University Cooperative Research Center for Advanced Electronics Interconnects," \$30,000, Principal Investigator, March 1, 1993 - February 28, 1994.

U.S. Army Research Office, "Automated Finite Element Modeling of Circuit Card Assemblies," \$100,000, Principal Investigator, July 1, 1991- June 30, 1993.

Research Venture Award, "Industry/University Cooperative Research Center for Advanced Electronics Interconnect," \$67,400, Principal Investigator, 1993.

Indianapolis Research Support Committee, "Development of Manufacturing Productivity Software Laboratory," \$48,581, Principal Investigator, 1991.

Indianapolis Research Support Committee, "Instrumentation Fund," \$20,000, Principal Investigator, 1990.

PDP University/Industry (**Indianapolis Heliport Corporation**) Cooperative Grant, "Aircraft Accessory Development Program," \$11,000, Principal Investigator, April 1, 1989 - March 30, 1990.

Indiana Department of Commerce, Indianapolis, Indiana, "Minimum Weight Shell Design," \$2,800, Principal Investigator, September 1989 August 1990.

Purdue University XL Grant, "Analytical and Experimental Investigation of Variable Thickness Sandwich Plates of Rectangular Planform," \$3,900, Principal Investigator, Summer 1988.

Program Development (internal) Grants:

Women in Engineering and Technology Grant, FASPAC, **IUPUI**, \$131,000, 1998-2004.

Graduate Program Enhancement, **IUPUI**, \$387,640, 1997-2003.

IUPUI Research Investment Fund, "Biomechanics and Biomaterials Research Center," \$222,630, Principal Investigator, 1990.

PUBLICATIONS:

Paydar, N., L. Richards V. Borden, and M. Vanderpool, "Using Enrollment Research as a Compass for Institutional Transitions" National Conference on Student Recruitment, Marketing, and Retention, Chicago, IL, July 15 – 17, 2008.

Paydar, N., "Higher Education Enrollment Trends," Annual Conference of American Society for Engineering Education (ASEE), Montreal, Canada, June 2002.

Paydar, N., "Global Enrollment Trends in Higher Education," American Society for Engineering Education (ASEE) Colloquium, Berlin, Germany, October 2002.

Akay, H.U., G. Kaliappan, **N. Paydar**, and M. Rassaian, "A Study of Fatigue Life Predictions for PBGA Joints and Comparisons with Test Data," Proceedings of ASME InterPACK '99, Maui, Hawaii, June 13-19, 1999.

H.U. Akay, **N. Paydar**, G. Glogas, and H. Zhang, "Viscoelastic Study of a Conductive Adhesive for Electronic Packages – Part 1: Experimental Determination of Material Properties," *International Journal of Microelectronic Packaging*, vol. 1, 1998, pp. 217-224.

Akay, H.U., **N. Paydar**, G. Glogas, and H. Zhang, "Viscoelastic Study of a Conductive Adhesive for Electronic Packages – Part 2: Experimental Determination of Material Properties," *International Journal of Microelectronic Packaging*, vol. 1, 1998, pp. 225-233.

Winkler, M.M., T.R. Katona, **N. Paydar**, "Finite Element Stress Analysis of Three Filling Techniques for Class V Light-Cured Composite Restorations," *Journal of Dental Research*, Under Review, 1996.

Fisher, D.A., A.C. Tsang, **N. Paydar**, S. Milionis, C.H. Turner, "Cement Mantle Thickness Affects Cement Strains in Total Hip Replacement," *Journal of Orthopaedic Research*, Under Review, 1996.

Burr, D., D. Dankert, Y. Takano, H. Akay, **N. Paydar**, J. Haskett, M. Forwood, R. Boyd, and M. Schaffler, "Correlation of High Strains with Stress Fracture Site Using Experimental and Computational Analysis in an Animal Model," *Journal of Biomechanics*, Under Review, 1996.

Akay, H.U., **N. Paydar**, X. Song, and G. Glogas, "Creep Response Comparisons of Adhesive and Solder Joints Under Thermal Loads Using the Finite Element Method," *ASME Journal of Electronic Packaging*, Under Review, 1996.

- Burr, D., H. U. Akay, **N. Paydar**, J. Haskett, and S. Mori, "Laboratory Measurement and Numerical Evaluation of Mechanical Function and Biological Adaptation in Skeletal Tissues," *American Journal of Physical Anthropology*, in press, 1996.
- H.U. Akay, **N. Paydar**, X. Song, and G. Glogas, "Viscoelastic Finite Element Analysis of Adhesive Joints Under Thermal Loads," Proceedings of ASME INTERPack '95, March 26-30, 1995, Lahaina, Hawaii.
- Fisher, D.A., A.C. Tsang, **N. Paydar**, S. Milionis, and C.H. Turner, "Effects of Cement Mantle Thickness of Cement Strains in the Femoral Stem of Total Hip Arthroplasty," 41st Annual Meeting of Orthopaedic Research Society, Orlando, Florida, February 13-16, 1995.
- Katona, T.R., **N. Paydar**, H.U. Akay, and W.E. Roberts, "Stress Analysis of Bone Modeling Response to Rat Molar Orthodontics," *Journal of Biomechanics*, Vol. 28, No. 1, pp. 27-38, 1995.
- Paydar, N.**, Y. Tong, and H.U. Akay, "A Finite Element Study of Factors Affecting Fatigue Life of Solder Joints," *ASME Journal of Electronic Packaging*, vol. 116, no. 4, pp. 265-273, 1994.
- Paydar, N.**, Y. Tong, and H.U. Akay, " An Investigation of Three-Dimensional Effects in Modeling of Solder Joints for Fatigue Life Predictions," International Microelectronics Conference, April 20-22, IMC 1994, pp. 367-372, 1994.
- Chen, J., X. Lu, **N. Paydar**, H. U. Akay, and W.E. Roberts, "Mechanical Simulation of the Human Temporomandibular Joint With and Without Endosseous Implant," *Journal of Medical Engineering Physics*, vol. 16, pp. 53-61, 1994.
- Paydar, N.**, H.U. Akay, J. Haskett, D. Burr, "Stress Fractures in a Rabbit Tibia - Experimental and Finite Element Studies," *Journal of Biomechanics*, vol 26, no 7, 1993.
- Paydar, N.**, Y. Tong, and H.U. Akay, " A Finite Element Study of Fatigue Life Prediction Method for Thermally Loaded Solder Joints," EEP-Vol. 4-2, Advances in Electronic Packaging, Edited by P.A. Engel and W.T. Chen, ASME Book No. 10349B, pp. 1063-1070, 1993.
- Paydar, N.**, H.U. Akay, J. Haskett, D. Burr, " Computer Simulation of a Rabbit Tibia for Stress Fracture," IVth International Symposium on Computer Simulation in Biomechanics, Paris, France, June 30-July 2, pp. BOAFF1: 14-15, 1993.

- Akay, H.U., Y. Tong, and **N. Paydar**, "Thermal Fatigue Analysis of an SMT Solder Joint Using Nonlinear FEM Approach," *International Journal of Microcircuits & Electronic Packaging*, vol 16, No. 2, pp. 79-88, 1993.
- Akay, H.U., Y. Tong, and **N. Paydar**, "Thermal Fatigue Analysis of an SMT Solder Joint Using Nonlinear FEM Approach," International Electronics Packaging Conference, Austin Texas, September 27-30, 1992, IEPC Proceedings, pp. 980-998.
- Paydar, N.**, H.U. Akay, J. Haskett, D. Burr, "Stress Fractures in a Rabbit Tibia - Experimental and Finite Element Studies," 8th European Society of Biomechanics Meeting, Rome, Italy, June 21-24, 1992.
- Chen, J., X. Lu, **N. Paydar**, H.U. Akay, and W.E. Roberts, "An Investigation of Mechanical Environment within the Human Mandible with and without Endosseous Implant," Proceedings of the ASME Winter Annual Meeting, Bioengineering Division, Anaheim, CA, November 8-13, 1992, BED-Vol 22, Advances in Bioengineering, pp. 301-304.
- Burr, D.B., H.U. Akay, **N. Paydar**, and S. Mori, "Locally High Shear Stresses are Associated with Stress Fracture Location," Proceedings of the 38th Annual Meeting, Orthopaedic Research Society, Washington, D.C., February 17-20, 1992, Proceedings of ORS, p. 539.
- Chen, J., **N. Paydar**, H.U. Akay, and W.E. Roberts, "Mechanical Simulation of the Human Mandible with an Endosseous Implant," *Journal of Dental Research*. vol. 71, p. 528, 1992.
- Paydar, N.**, W.E. Roberts, H.U. Akay, T.R. Katona, B. Guthrie, "Finite Element Model of Osteoblast Differentiation in Periodontal Ligament," *Journal of Dental Research*. 70, p. 552, 1991.
- Paydar, N.**, H.U. Akay, T.R. Katona, and W.E. Roberts, "Finite Element Analysis of the Orthodontic Response in Rat Molar Periodontium," Proceedings of the ASME Winter Annual Meeting, Bioengineering Division, Atlanta, Georgia, December 1-6, BED - vol. 20, Advances in Bioengineering pp. 159-162, 1991.
- Paydar, N.**, H.U. Akay, C.L. Poyraz, and W.E. Roberts, "Finite Element Model of a Human Mandible for Investigating Joint Reactions and Bone Stresses During Mastication," Proceedings of the ASME Winter Annual Meeting, Bioengineering Division, Atlanta, Georgia, December 1-6, BED - vol. 20, Advances in Bioengineering, pp. 163-166, 1991.

- Katona, T.R., L.P. Garetto, **N. Paydar**, H.U. Akay, and W.E. Roberts, "Osteoblast Histogenesis in Rat Periodontal Ligament Following Orthodontic Stimulation," A Combined Approach Using Cell Kinetics and Finite Element Modeling, Symposium on Undecalcified Bone technology, Indianapolis, Indiana, October 25-26, 1991.
- Paydar, N.**, H.U. Akay, and Y.H. Tong, "Thermal Stress Analysis of an SMT Solder Joint Using a Creep-Plasticity Model," Proceedings of Electrecon '91, Indianapolis, Indiana, pp. 113-124, October 22-23, 1991.
- Katona, T.R., L.P. Garetto, **N. Paydar**, H.U. Akay, and W.E. Roberts, "Finite Element Model of Bone Cell Kinetics," Proceedings of the 23rd International Sun Valley Workshop on Hard Tissue Biology, Sun Valley, Idaho, August 4-9, 1991.
- Paydar, N.**, W.E. Roberts, H.U. Akay, T.R. Katona, and B. Guthrie "Finite Element Model of Osteoblast Differentiation in Periodontal Ligament," I/AADR Annual Session, Acapulco, Mexico, April 17-21, 1991.
- Paydar, N.** "Axisymmetric Buckling of Annular Sandwich Plate of Variable Thickness," *Journal of Composite Structure*, vol. 15, pp. 149-159, 1990.
- Roberts, W.E., **N. Paydar**, and H.U. Akay, "Finite Element Analysis of Mechanically Induced Bone Formation in Rat Molar Periodontal Ligament," ASGSB Bulletin 4:33, 1990.
- Paydar, N.**, and G.J. Park, "Optimal Design of Sandwich Beams," *Journal of Computers and Structures*, vol. 34, no. 4, pp. 523-526, 1990.
- Paydar, N.**, and G.J. Park "Optimal Design of Sandwich Beams with Linear Thickness Variation," *Journal of Composite Material Technology*, vol. 32, pp. 27-30, 1990. Also presented at the Energy Resources Technology Conference and Exhibition, New Orleans, Louisiana, January 14-18, 1990.
- Paydar, N.**, and G.J. Park, "Minimum Weight Sandwich Beam Design," Proceedings of the 21st Midwestern Mechanics Conference, Michigan Technological University, Houghton Michigan, August 13-16, 1989, Also published in *Developments in Mechanics*, vol. 15, pp. 457-458, 1989.
- Paydar, N.**, and D. Afolabi, "Buckling Analysis of Tapered Sandwich Plates," Proceedings of 21st Midwestern Mechanics Conference, Michigan Technological University, Houghton, Michigan, August 13-16, 1989, Also published in *Developments in Mechanics*, vol. 15, pp. 195-196, 1989.

- Paydar, N.**, and R. Adams, "Transverse Vibrations of Annular Sandwich Plates of Variable Thickness," *Journal of Sound and Vibration*, vol. 131 (2), pp. 259-263, June 1989.
- Paydar, N.**, and C. Libove, "Bending of Sandwich Plates of Variable Thickness," Proceedings of the ASME Winter Annual Meeting, Paper no. 88-WA/APM-40, Chicago, IL, December 1988.
- Paydar, N.**, "Effects of Mechanical Loads on Sandwich Plates of Variable Thickness," ASME Pressure Vessels and Piping. Advances in Macro-mechanics of Composite Material Vessels and Components, vol. 146, pp. 63-68, June 1988.
- Paydar, N.**, "Buckling Analysis of Sandwich Columns of Linearly Varying Thickness," *AIAA Journal (American Institute of Aeronautics and Astronautics Journal)*, vol. 26, pp. 756-759, June 1988.
- Paydar, N.**, and C. Libove, "Bending of Sandwich Plates of variable Thickness," *ASME Transaction Journal of Applied Mechanics*, vol. 55, no. 2, pp. 419-424, June 1988.
- Paydar, N.**, "Stress Analysis of Annular Sandwich Plates of Linearly Varying Thickness," *International Journal of Solids and Structures*, vol. 24, pp. 313-320, April 1988.
- Paydar, N.**, and R. Adams, "Axisymmetric Vibration of Annular Sandwich Plates of Linearly Varying Thickness," Proceedings of the 20th Midwestern Mechanics Conference, Purdue University, West Lafayette, Indiana, August 31 - September 2, 1987, Also published in Developments in Mechanics, vol. 14c, pp. 1072-1077, 1987.
- Paydar, N.**, "Effects of Mechanical and Thermal Loads on Variable Thickness Sandwich Plates of Rectangular Planform," Proceedings of the 20th Midwestern Mechanics Conference, Purdue University, West Lafayette, Indiana, August 31 - September 2, 1987, Also published in Developments in Mechanics, vol. 14c, pp. 1066-1071, 1987.
- Paydar, N.**, and C. Libove, "Stress Analysis of Sandwich Plates with Unidirectional Thickness Variation," *ASME Transaction Journal of Applied Mechanics*, September 1986, Vol. 53, pp. 609-613. Also presented at the ASME Winter Annual Meeting, Paper No. 86-WA/APM 40, December 1986, Anaheim, California